

Statement of Compliance

Requested Part

23 April 2014

1761606-3

(Part 1 of 1)

IDC LOW PRO HDR 10P VERT LG LAT BLK

Part Status:	Active
EU RoHS/ELV Code:	Always EU RoHS/ELV Compliant
Solder Process Capability Code:	Wave solder capable to 265°C
China RoHS:	No Restricted Materials Above Threshold

None

Exemptions:	Ν
REACH Oct 2008 SvHC Compliance:	C
REACH Jan/Mar 2010 SvHC Compliance:	С
REACH June 2010 SvHC Compliance:	С
REACH December 2010 SvHC Compliance:	C
REACH June 2011 SvHC Compliance:	С
REACH December 2011 SvHC Compliance:	C
REACH June 2012 SvHC Compliance:	C
REACH December 2012 SvHC Compliance:	С
REACH June 2013 SvHC Compliance:	Ν
REACH December 2013 SvHC Compliance:	Ν
Halogen Content:	Ν
Material Declarations:	Ν

Contains no REACH October 2008 SvHC(s) Contains no REACH Jan/Mar 2010 SvHC(s) Contains no REACH June 2010 SvHC(s) Contains no REACH December 2010 SvHC(s) Contains no REACH June 2011 SvHC(s) Contains no REACH December 2011 SvHC(s) Contains no REACH December 2012 SvHC(s) Contains no REACH December 2012 SvHC(s) Not Reviewed for REACH June 2013 SvHC(s) Not reviewed for REACH December 2013 SvHC(s) Not reviewed for REACH December 2013 SvHC(s) Not Low Halogen - contains Br or Cl > 900 ppm. MD_1761606-3

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Guy Degrieck Manager, Product Environmental Compliance

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Note that any exemptions taken in this case would not include application specific exemptions (e.g. lead in solder for servers) as TE cannot determine where component products will be used.

Additionally, the part numbers that are identified as 5 of 6 compliant meet the material limits described above, except that these products have lead in the solderable interface only. These products may be suitable for use in an application that has an exemption for the use of lead in solder (e.g. servers, network infrastructure, etc).

Finished electrical and electronic products will be CE marked as required by Directive 2011/65/EU (RoHS2). Components may not be CE marked.

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change.